AMENDMENTS TO THE CLAIMS

1. (Currently Amended) An optical semiconductor component, comprising:

a plurality of conducting wire holders;

a plurality of independent chip carriers secured on the conducting wire holders, wherein the independent chip carriers have a multi-layer structure, middle layers of the independent chip carriers being insulators used to separate the semiconductors from the conducting wire holders;

a plurality of semiconductor chips secured on the independent chip carriers;

a first curved surface made of a portion of the conducting wire holders, wherein the semiconductor chips are placed at a focus of the first curved surface;

a plurality of independent connecting components made of another portion of the conducting wire holders; and

a second curved surface surrounded by a package body, wherein the semiconductor chips are placed at a focus of the second curved surface.

2. (Cancelled)

3. (Currently Amended) The optical semiconductor component as claimed in ~~claim 2~~claim 1, wherein upper surfaces of the independent chip carriers are conductors used to electrically connect with the semiconductor chips.

4. (Cancelled)

5. (Currently Amended) The optical semiconductor component as claimed in ~~claim 2~~claim 1, wherein lower surfaces of the independent chip carriers are conductors or insulators.

6. (Original) The optical semiconductor component as claimed in claim 1, wherein the first curved surface is coated with a material able to enhance a reflective capability.

7. (Original) The optical semiconductor component as claimed in claim 6, wherein the first curved surface is a paraboloidal or an ellipsoidal surface.

8. (Original) The optical semiconductor component as claimed in claim 1, wherein a portion of the independent connecting components is located inside the package body for electrically connecting with the semiconductor chips and another portion of the independent connecting components is projected from the package body for electrically connecting an external circuit.

9. (Original) The optical semiconductor component as claimed in claim 1, wherein the second curved surface is made of or coated with a material able to enhance a reflective capability.

10. (Original) The optical semiconductor component as claimed in claim 9, wherein the second curved surface is a paraboloidal or an ellipsoidal surface.

11. (Original) The optical semiconductor component as claimed in claim 10, wherein the second curved surface is a smooth surface.

12. (Original) The optical semiconductor component as claimed in claim 1, further comprising a window for light to pass through, wherein the window is formed by the first curved surface and the second curved surface.

13. (Original) The optical semiconductor component as claimed in claim 12, wherein the semiconductor chips and the independent chip carrier are placed inside the window.

14. (Original) The optical semiconductor component as claimed in claim 12, wherein the window is covered by a transparent optical component.

15. (Original) The optical semiconductor component as claimed in claim 14, wherein the transparent optical component is a planar lens, a convex lens or a concave lens.

16. (New) An optical semiconductor component, comprising:

a plurality of conducting wire holders;

a plurality of independent chip carriers secured on the conducting wire holders;

a plurality of semiconductor chips secured on the independent chip carriers;

a first curved surface made of a portion of the conducting wire holders, wherein the semiconductor chips are placed at a focus of the first curved surface;

a plurality of independent connecting components made of another portion of the conducting wire holders; and

a second curved surface surrounded by a package body, wherein the semiconductor chips are placed at a focus of the second curved surface;

wherein the first curved surface is coated with a material able to enhance a reflective capability.

17. (New) The optical semiconductor component as claimed in claim 16, wherein the first curved surface is a paraboloidal or an ellipsoidal surface.

18. (New) An optical semiconductor component, comprising:

a plurality of conducting wire holders;

a plurality of independent chip carriers secured on the conducting wire holders;

a plurality of semiconductor chips secured on the independent chip carriers;

a first curved surface made of a portion of the conducting wire holders, wherein the semiconductor chips are placed at a focus of the first curved surface;

a plurality of independent connecting components made of another portion of the conducting wire holders; and

a second curved surface surrounded by a package body, wherein the semiconductor chips are placed at a focus of the second curved surface;

wherein the second curved surface is made of or coated with a material able to enhance a reflective capability.

19. (New) The optical semiconductor component as claimed in claim 18, wherein the second curved surface is a paraboloidal or an ellipsoidal surface

20. (New) The optical semiconductor component as claimed in claim 19, wherein the second curved surface is a smooth surface.